

GSM3619KA

30V P-Channel MOSFET

Product Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency fast switching applications.

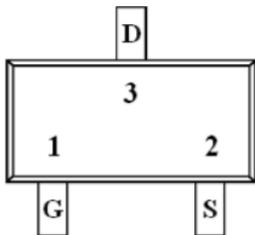
Features

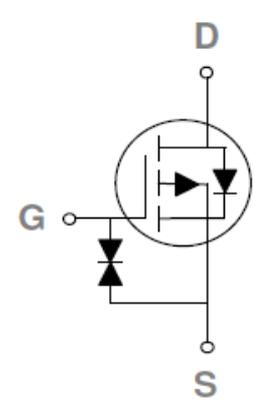
- -30V,-0.55A, $R_{DS(ON)} = 1\Omega @ V_{GS} = -4.5V$
- Fast switching
- Green Device Available
- Suit for -2.5V Gate Drive Applications

Applications

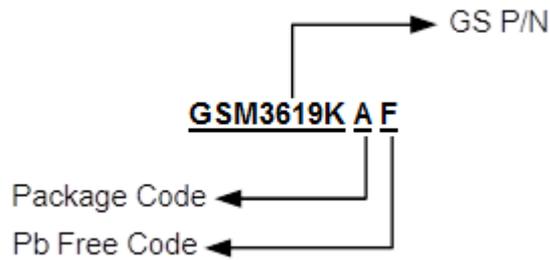
- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Packages & Pin Assignments

GSM3619KAF (SOT-723)	
 <p>Top View</p>	
Pin	Description
1	Gate
2	Source
3	Drain

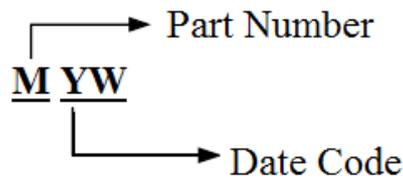


Ordering Information



Part Number	Package	Part Marking	Quantity
GSM3619KAF	SOT-723	MYW	8000pcs

Marking Information



Absolute Maximum Ratings

T_C=25°C Unless otherwise noted

Symbol	Parameter	Typical	Unit
V _{DS}	Drain-Source Voltage	-30	V
V _{GS}	Gate-Source Voltage	±12	V
I _D	Continuous Drain Current	T _A =25°C	-0.55
		T _A =70°C	-0.44
I _{DM}	Pulsed Drain Current ¹	-2.28	A
P _D	Power Dissipation	0.45	W
	Power Dissipation-Derate above 25°C	0.004	W/°C
T _J	Operating Junction Temperature Range	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C
R _{θJA}	Thermal Resistance-Junction to Ambient	280	°C/W

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

Electrical Characteristics

T_J=25°C Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30			V
$\frac{\Delta V_{(BR)DSS}}{\Delta T_J}$	V _{(BR)DSS} Temperature Coefficient	Reference to 25°C, I _D =-1mA		-0.015		V/°C
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250uA	-0.5	-0.7	-1.2	V
$\Delta V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-1.78		mV/°C
I _{GSS}	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±12V			±40	nA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-30V, V _{GS} =0V			-1	uA
		V _{DS} =-24V, V _{GS} =0V T _J =125°C			-10	
I _S	Continuous Source Current	V _G =V _D =0V, Force Current			-0.55	A
I _{SM}	Pulsed Source Current				-1.1	A
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} = -4.5V, I _D = -0.3A		780	1000	mΩ
		V _{GS} = -2.5V, I _D = -0.2A		1160	1600	
g _{FS}	Forward Transconductance	V _{DS} =-4V, I _D =-0.3A		0.8		S
V _{SD}	Diode Forward Voltage	I _S =-0.3A, V _{GS} =0V			-1	V

Electrical Characteristics (Continue)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Dynamic						
Q _g	Total Gate Charge ^{2,3}	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-0.3A	-	3.12	6.2	nC
Q _{gs}	Gate-Source Charge ^{2,3}		-	1.3	2.6	
Q _{gd}	Gate-Drain Charge ^{2,3}		-	0.5	1	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	-	73.4	146	pF
C _{oss}	Output Capacitance		-	19.1	38	
C _{rss}	Reverse Transfer Capacitance			12.1	25	
t _{d(on)}	Turn-On Time ^{2,3}	V _{DD} =-15V, I _D =-1A, V _{GS} =-10V, R _G =6Ω		7.4	15	ns
t _r	Rise Time ^{2,3}			21.5	43	
t _{d(off)}	Turn-Off Time ^{2,3}			46.9	92	
t _f	Fall Time ^{2,3}			14.4	29	

Note :

- The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
- Essentially independent of operating temperature.

Typical Performance Characteristics

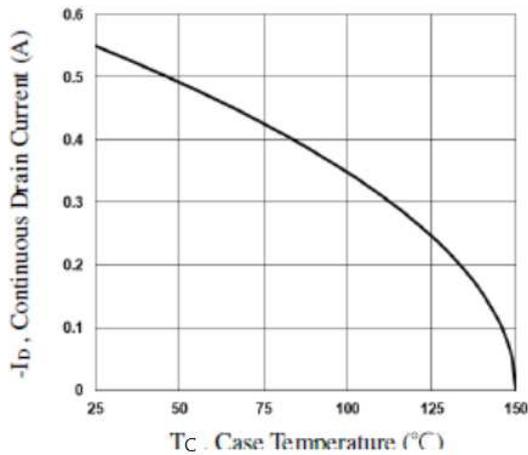


Fig.1 Continuous Drain Current vs. T_c

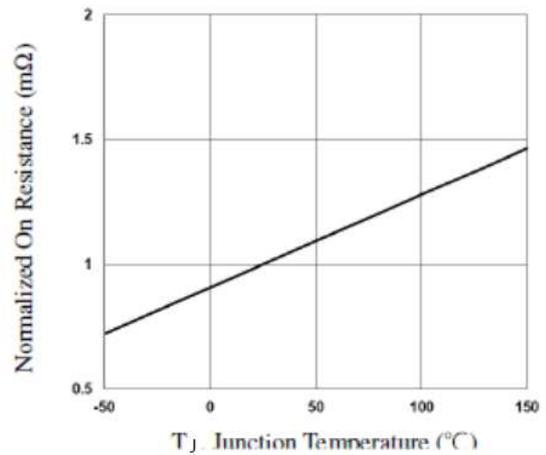


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

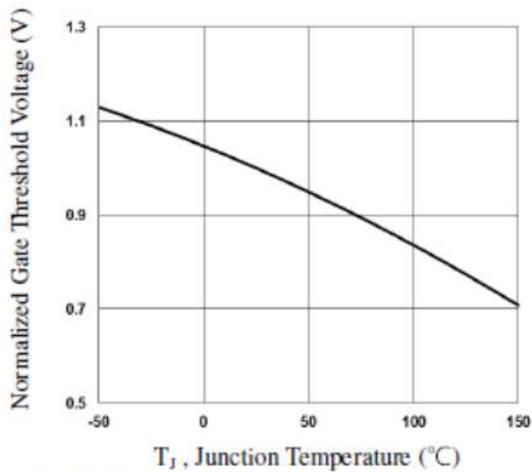


Fig.3 Normalized V_{th} vs. T_j

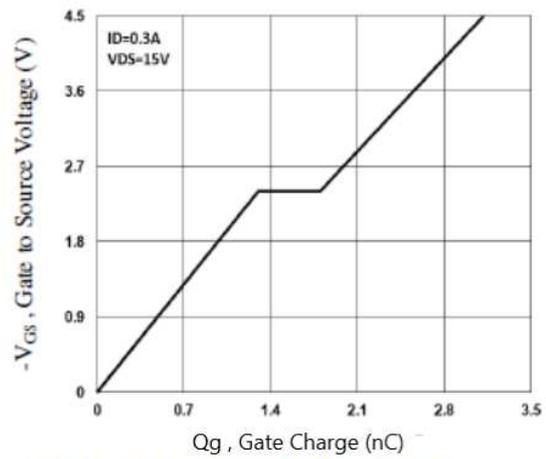


Fig.4 Gate Charge Waveform

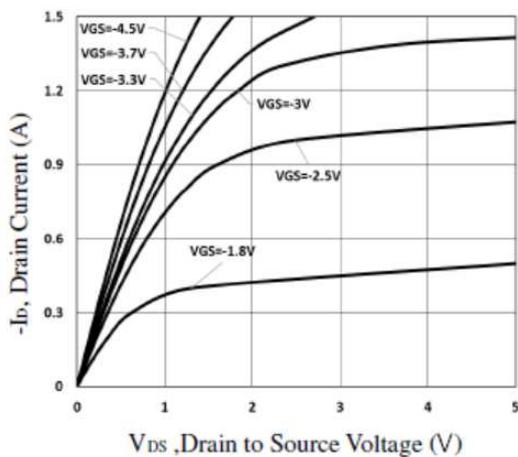


Fig.5 Typical Output Characteristics

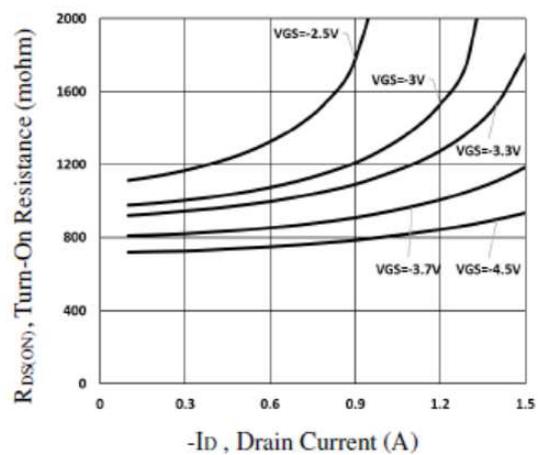


Fig.6 Turn-On Resistance vs. I_D

Typical Performance Characteristics (Continue)

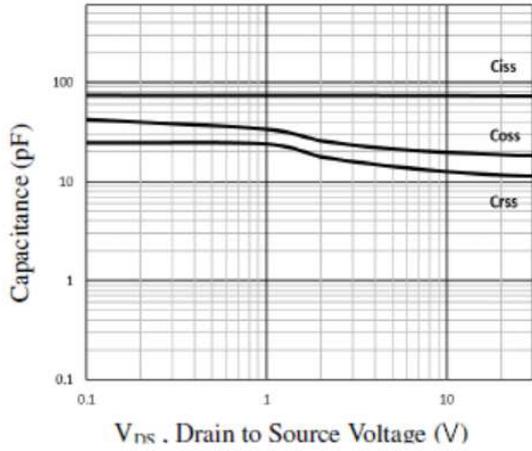


Fig.7 Capacitance Characteristics

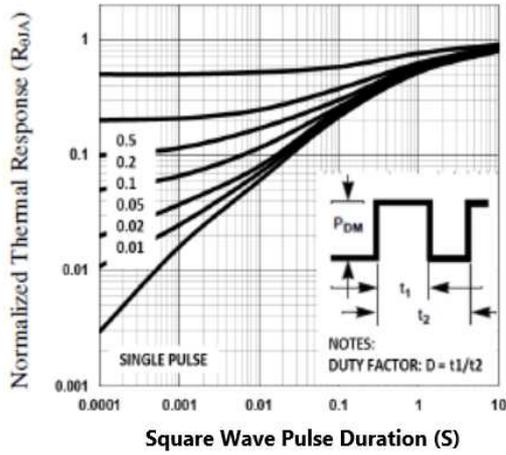


Fig.8 Normalized Transient Impedance

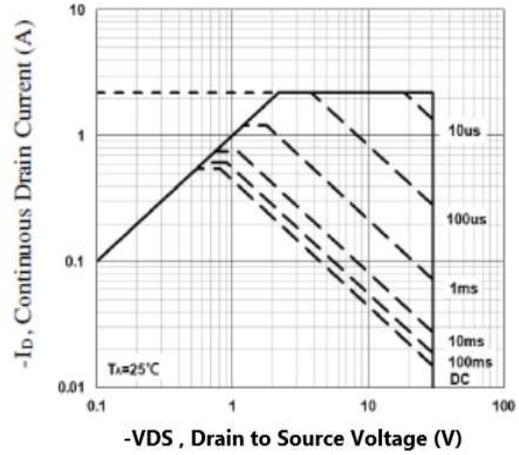


Fig.9 Maximum Safe Operation Area

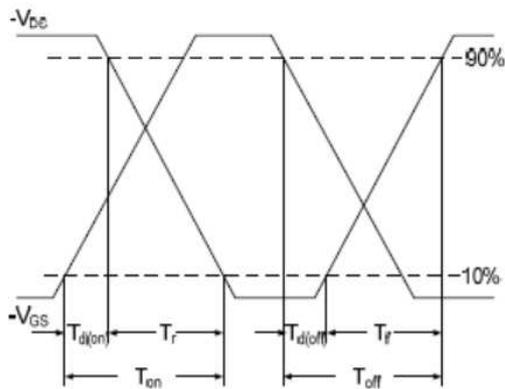


Fig.10 Switching Time Waveform

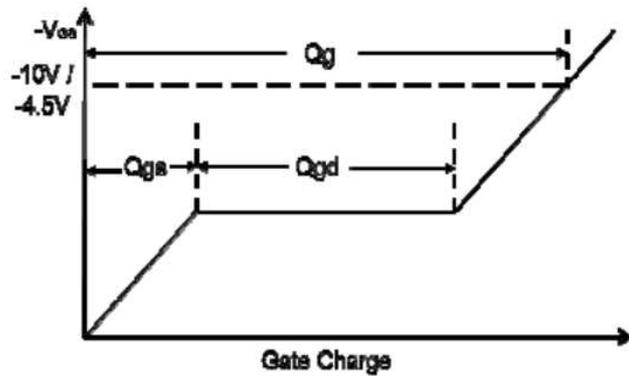
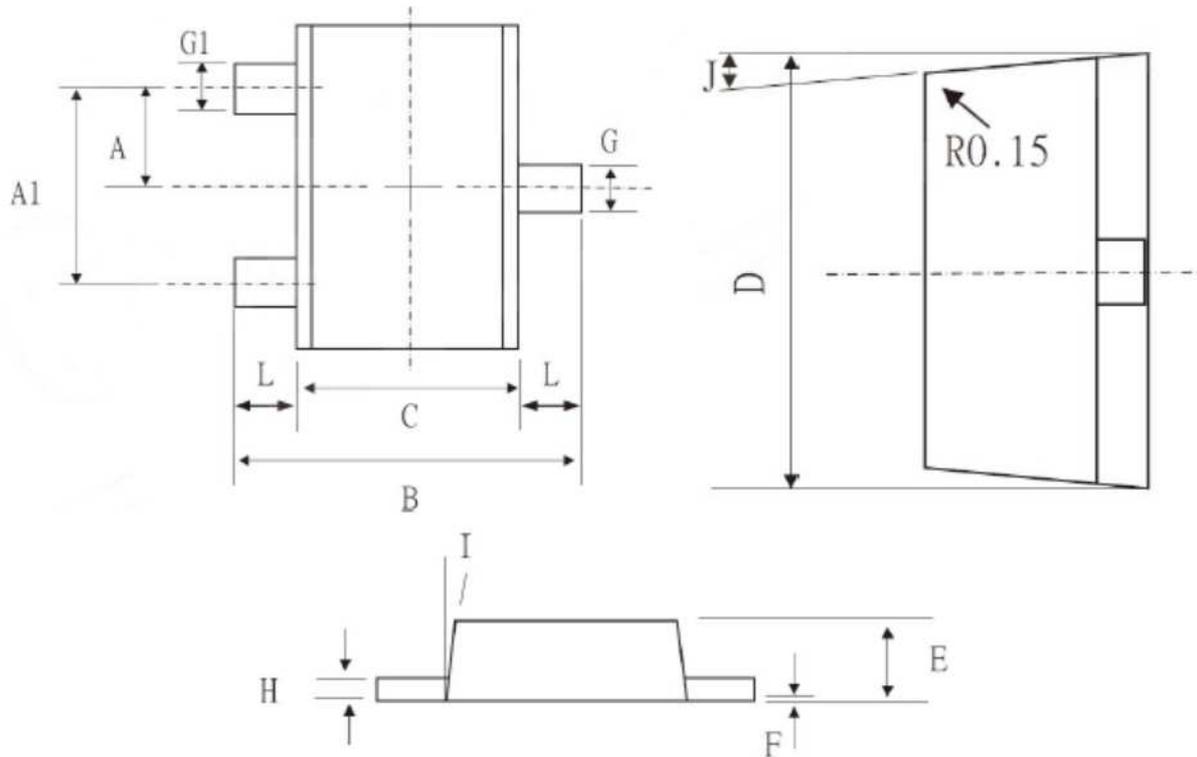


Fig.11 Gate Charge Waveform

Package Dimension

SOT-723



Dimensions				
SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.4BSC		0.016BSC	
A1	0.8BSC		0.031BSC	
B	1.250	1.150	0.049	0.045
C	0.850	0.750	0.033	0.030
D	1.250	1.150	0.049	0.045
E	0.390	0.370	0.015	0.015
F	0.050	0.000	0.002	0.000
G	0.270	0.220	0.011	0.009
G1	0.220	0.170	0.009	0.007
H	0.110	0.009	0.004	0.000
I	13°	9°	13°	9°
L	0.250	0.150	0.010	0.006
J	11°	7°	11°	7°

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